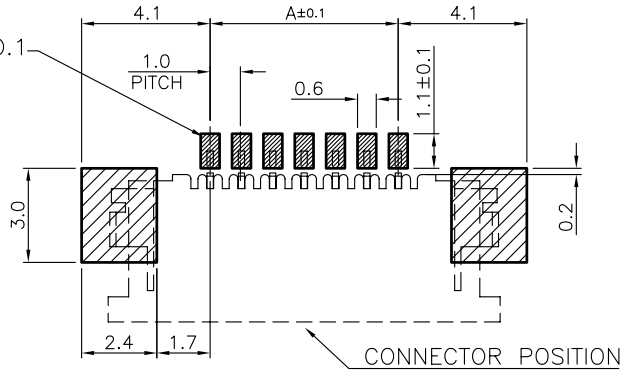


RECOMMENDED APPLICABLE FPC LAYOUT
(THICKNESS:0.3±0.03)



PCB PATTERN LAYOUT

NOTES:

- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0;
 - CONTACT: COPPER ALLOY
 - FITTING NAIL: COPPER ALLOY
- FINISH:
 - CONTACT:
 - 50u" MIN. NICKEL UNDERPLATING OVERALL.
 - 1: GOLD FLASH OVERALL.
 - FITTING NAIL:
 - 50u" MIN. NICKEL UNDERPLATING OVERALL.
 - 1: GOLD FLASH OVERALL.
- REFLOW SOLDER CAPABLE TO 260° C PER ACES SPEC.
- SPEC. PLS. REFER TO SPEC-50634-XXXX-XXX.
- PACKAGE PLS. REFER TO 87151-XXX3-TRP.

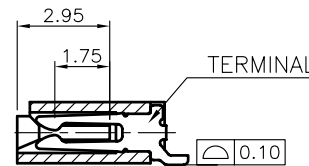
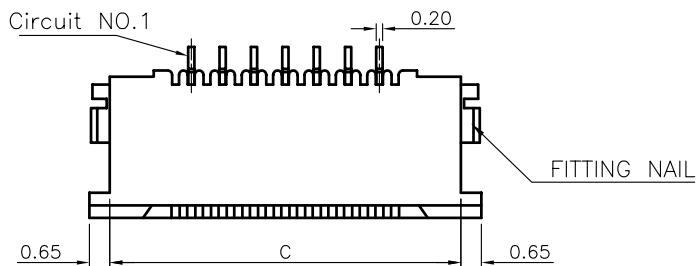
P/N LEGEND

50639-XXX X X -XXX

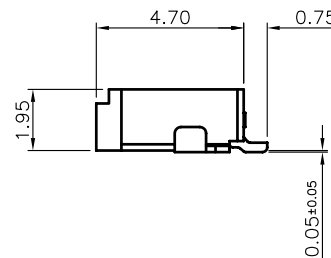
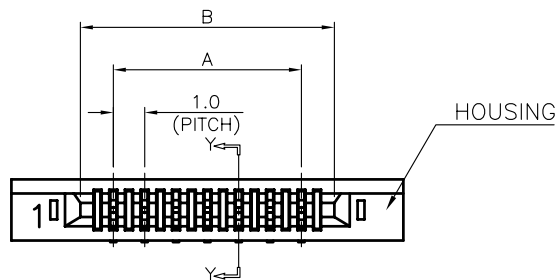
NO OF CKT

XXX	Housing MAT.	Housing Color.	Halogen Free
001	HF PLASTIC	BLACK	HF

PLATING
1:G/F OVER ALL(LEAD FREE)
N:MATT TIN(LEAD FREE)
PACKING
0:TAPE & REEL
1:TUBE



SEC. Y-Y



CKT	Dim A	Dim B	Dim C	CKT	Dim A	Dim B	Dim C
4	3.0	5.1	8.2	19	18.0	20.1	23.2
5	4.0	6.1	9.2	20	19.0	21.1	24.2
6	5.0	7.1	10.2	21	20.0	22.1	25.2
7	6.0	8.1	11.2	22	21.0	23.1	26.2
8	7.0	9.1	12.2	23	22.0	24.1	27.2
9	8.0	10.1	13.2	24	23.0	25.1	28.2
10	9.0	11.1	14.2	25	24.0	26.1	29.2
11	10.0	12.1	15.2	26	25.0	27.1	30.2
12	11.0	13.1	16.2	27	26.0	28.1	31.2
13	12.0	14.1	17.2	28	27.0	29.1	32.2
14	13.0	15.1	18.2	29	28.0	30.1	33.2
15	14.0	16.1	19.2	30	29.0	31.1	34.2
16	15.0	17.1	20.2	31	30.0	32.1	35.2
17	16.0	18.1	21.2	32	31.0	33.1	36.2
18	17.0	19.1	22.2				

一般公差 TOLERANCES X ±0.5 XX ±0.15 X ±0.25 XXX ±0.1 ANGLES ±2°		宏致電子股份有限公司 Aces Electronic Co.,Ltd.	
檢驗尺寸標示 SYMBOLS INDICATE CLASSIFICATION DIMENSION MARK IS CRITICAL DIM. MARK IS MAJOR DIM.		品名 (TITLE) 1.0mm NON ZIF FPC CONN. SMT R/A TYPE 圖號 (DWG.NO) 50639-XXXXX-XXX	
表面處理 (FINISH)		製圖 (DR) SHM 11/05/31 審核 (CHKD) CARL 核准 (APPD) Jason	
比例 (SCALE) 4:1 單位 (UNITS) mm		張數 (SHEET) 1 OF 1 圖號 (DWG.NO) 50639-XXXXX-XXX 圖號 (DWG.NO) 50639-XXXXX-XXX	